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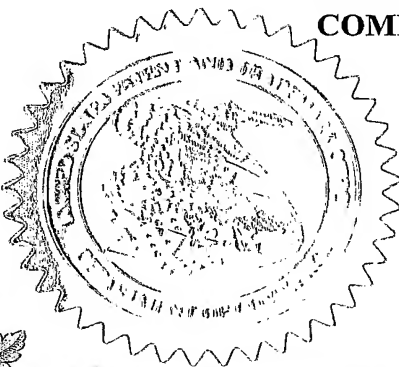
APPLICATION NUMBER: 10/939,269

FILING DATE: September 10, 2004

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UTILITY
PATENT APPLICATION
TRANSMITTAL

(Only for new nonprovisional applications under 37 CFR 1.53(b))

Attorney Docket No.

Serie 6550

First Inventor

Ashutosh Misra

Title

Novel Deposition of High-K MSION Dielectric Films

Express Mail Label No.

EV 534767890 US

APPLICATION ELEMENTS

See MPEP chapter 600 concerning utility patent application contents.

ADDRESS TO:

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1. ☒ Fee Transmittal Form (e.g., PTO/SB/17)
(Submit an original and a duplicate for fee processing)
2. ☐ Applicant claims small entity status.
See 37 CFR 1.27.

3. ☒ Specification (Total Pages 16)
(preferred arrangement set forth below)
- Descriptive title of the invention
 - Cross Reference to Related Applications
 - Statement Regarding Fed sponsored R & D
 - Reference to sequence listing, a table, or a computer program listing appendix
 - Background of the invention
 - Brief Summary of the invention
 - Brief Description of the Drawings (if filed)
 - Detailed Description
 - Claim(s)
 - Abstract of the Disclosure

4. ☒ Drawing(s) (35 U.S.C. 113) (Total Sheets 1)

5. Oath or Declaration (Total Sheets)

- a. ☐ Newly executed (original or copy)
- b. ☐ Copy from a prior application (37 CFR 1.63(d))
(for continuation/divisional with Box 18 completed)
- i. ☐ **DELETION OF INVENTOR(S)**
Signed statement attached deleting inventor(s)
name in the prior application, see 37 CFR
1.63(d)(2) and 1.33(b).

6. ☐ Application Data Sheet. See 37 CFR 1.76

7. ☐ CD-ROM or CD-R in duplicate, large table or
Computer Program (Appendix)
8. Nucleotide and/or Amino Acid Sequence Submission
(if applicable, all necessary)

- a. ☐ Computer Readable Form (CRF)

- b. Specification Sequence Listing on:

- i. ☐ CD-ROM or CD-R (2 copies); or

- ii. ☐ Paper

- c. ☐ Statements verifying identity of above copies

ACCOMPANYING APPLICATION PARTS

9. ☐ Assignment Papers (cover sheet & document(s))
10. ☐ 37 CFR 3.73(b) Statement ☐ Power of
(when there is an assignee) Attorney
11. ☐ English Translation Document (if applicable)
12. ☐ Information Disclosure ☐ Copies of IDS
Statement (IDS)/PTO-1449 Citations
13. ☐ Preliminary Amendment
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16. ☐ Nonpublication Request under 35 U.S.C. 122
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or its equivalent.
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18. If a CONTINUING APPLICATION, check appropriate box, and supply the requisite information below and in the first sentence of the specification following the title, or in an Application Data Sheet under 37 CFR 1.76:

☐ Continuation ☐ Divisional ☐ Continuation-in-part (CIP) of prior application No.:

Prior application Information:

Examiner:

Art Unit:

For CONTINUATION OR DIVISIONAL APPS only: The entire disclosure of the prior application, from which an oath or declaration is supplied under Box 5b, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference. The incorporation can only be relied upon when a portion has been inadvertently omitted from the submitted application parts.

19. CORRESPONDENCE ADDRESS

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Signature

[Signature]

Date

September 10, 2004

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PTO/SB/17 (10-03)

Approved for use through 07/31/2008. OMB 0651-0032
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE**FEE TRANSMITTAL
for FY 2004**

Effective 10/01/2003. Patent fees are subject to annual revision.

Applicant claims small entity status. See 37 CFR 1.27

Complete if Known

Application Number	Unknown
Filing Date	September 10, 2004
First Named Inventor	Ashutosh Misra
Examiner Name	Unknown
Art Unit	Unknown
Attorney Docket No.	Serie 6550

TOTAL AMOUNT OF PAYMENT (\$ 1,166.00

METHOD OF PAYMENT (check all that apply)
☐ Check ☐ Credit card ☐ Money Order ☐ Other ☐ None

Deposit Account:

Deposit
Account
Number
Deposit
Account
Name

01-1375

American Air Liquide, Inc.

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☐ Credit any overpayments☐ Charge any additional fee(s) or any underpayment of fee(s)☐ Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.**FEE CALCULATION****1. BASIC FILING FEE**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1001 770	2001 385	Utility filing fee	770.00
1002 340	2002 170	Design filing fee	
1003 530	2003 265	Plant filing fee	
1004 770	2004 385	Reissue filing fee	
1005 160	2005 80	Provisional filing fee	
SUBTOTAL (1)			(\$ 770.00)

2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

Total Claims	Extra Claims	Fee from below	Fee Paid
42	22**	18	396.00
2	3**	0	

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description
1202 18	2202 9	Claims in excess of 20
1201 86	2201 43	Independent claims in excess of 3
1203 290	2203 145	Multiple dependent claim, if not paid
1204 86	2204 43	** Reissue independent claims over original patent
1205 18	2205 9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$ 396.00

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity Small Entity

Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1051 130	2051 65	Surcharge - late filing fee or oath	
1052 50	2052 25	Surcharge - late provisional filing fee or cover sheet	
1053 130	1053 130	Non-English specification	
1812 2,520	1812 2,520	For filing a request for <i>ex parte</i> reexamination	
1804 920*	1804 920*	Requesting publication of SIR prior to Examiner action	
1805 1,840*	1805 1,840*	Requesting publication of SIR after Examiner action	
1251 110	2251 55	Extension for reply within first month	
1252 420	2252 210	Extension for reply within second month	
1253 950	2253 475	Extension for reply within third month	
1254 1,480	2254 740	Extension for reply within fourth month	
1255 2,010	2255 1,005	Extension for reply within fifth month	
1401 330	2401 165	Notice of Appeal	
1402 330	2402 165	Filing a brief in support of an appeal	
1403 290	2403 145	Request for oral hearing	
1451 1,510	1451 1,510	Petition to institute a public use proceeding	
1452 110	2452 55	Petition to revive - unavoidable	
1453 1,330	2453 665	Petition to revive - unintentional	
1501 1,330	2501 665	Utility Issue fee (or reissue)	
1502 480	2502 240	Design Issue fee	
1503 640	2503 320	Plant Issue fee	
1460 130	1460 130	Petitions to the Commissioner	
1807 50	1807 50	Processing fee under 37 CFR 1.17(q)	
1806 180	1806 180	Submission of Information Disclosure Stmt	
8021 40	8021 40	Recording each patent assignment per property (times number of properties)	
1809 770	2809 385	Filing a submission after final rejection (37 CFR 1.129(a))	
1810 770	2810 385	For each additional invention to be examined (37 CFR 1.129(b))	
1801 770	2801 385	Request for Continued Examination (RCE)	
1802 900	1802 900	Request for expedited examination of a design application	

Other fee (specify)

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$ 1,166.00

SUBMITTED BY

Name (Print/Type)	Linda K. Russell	Registration No. (Attorney/Agent)	34,918	Telephone	713-624-8956
Signature		Date	September 10, 2004		

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Application for United States Letters Patent

For

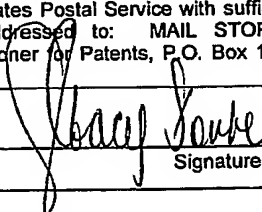
NOVEL DEPOSITION OF HIGH-K MSION DIELECTRIC FILMS

by

Ashutosh MISRA

Matthew FISHER

Benjamin JURCIK

CERTIFICATE OF EXPRESS MAILING UNDER 37 C.F.R. § 1.8	
EXPRESS MAIL NO.	EV 534767890 US
DATE OF DEPOSIT:	September 10, 2004
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NOVEL DEPOSITION OF HIGH-K MSiON DIELECTRIC FILMS

Cross-Reference

This application is related to and claims the benefit of U.S. Provisional
5 Application No. 60/550,908, filed March 5, 2004, entitled "Composition And
Method For Deposition Of High-k Dielectric Films."

Background

Manufacturing of semiconductor devices employs a thin gate
10 dielectric (typically silicon dioxide) between the underlying silicon substrate
and the gate electrode. Depositing a thin dielectric film on a silicon
substrate forms a gate dielectric. Typical processes for growth of dielectric
films include oxidation, chemical vapor deposition and atomic layer
deposition processes. As integrated circuit devices shrink, the thickness of
15 the gate dielectric needs to shrink proportionally. However, semiconductor
manufacturers have reached the limit to which the thickness of
conventional gate dielectric materials can be decreased without
compromising the electrical characteristics. Rather than degrading the
dielectric properties by using a silicon dioxide dielectric that is only a few
20 atomic layers thick, equivalent dielectric performance can be achieved by
substituting the silicon dioxide for a thicker layer of a new material
exhibiting a higher dielectric constant. Therefore, new compositions or
methods to produce a dielectric film with a higher dielectric constant than
silicon dioxide (referred to as "high-k dielectrics") are required. These
25 "high-k dielectrics" must have a low leakage current through the gate
dielectric. Thus, it is desirable to develop new compositions and methods of
depositing dielectric films with the required higher dielectric properties so
that films with more than one or two layers of atoms can be deposited. Due
to the requirements for thin dielectric films, having uniform coverage of

material that is very high quality is critical to the performance of the gate dielectric.

Of particular interest is the formation of metal silicon oxynitride ("MSiON") films. Forming a MSiON dielectric film typically involves feeding
5 a metal source, a silicon source, an oxygen source and a nitrogen source (collectively referred to herein as the "dielectric precursors") in the proper relative amounts to a deposition device wherein a silicon substrate is held at an elevated temperature. The dielectric precursors are fed to a deposition chamber through a "delivery system." A "delivery system" is the
10 system of measuring and controlling the amounts of the various dielectric precursors being fed to the deposition chamber. Various delivery systems are known to one skilled in the art. Once in the deposition chamber, the dielectric precursors react to deposit a dielectric film on the silicon substrate in a "forming" step. A "forming" step or steps, as used in this
15 application, is the step or steps wherein materials are deposited on the silicon substrate or wherein the molecular composition or structure of the film on the silicon substrate is modified. The "desired final composition" of the dielectric film is the precise chemical composition and atomic structure of the gate dielectric after the last forming step is complete. Compounds of
20 hafnium, such as hafnium oxides, hafnium silicates and hafnium silicon oxy nitrides are currently the most promising high-k gate dielectric choices. The metal source for the forming process is typically a liquid precursor solution containing the desired metal in a solvent. Similarly, the silicon sources available in the art prior to the current invention typically use a liquid
25 precursor containing the desired silicon compound in a solvent.

U.S. Patent Publication No. US 2003/0207549, PAJ Patent Application No. 2000272283, U.S. Patent No. 06399208, and U. S. Patent Publication No. 2003/0207549 disclose information relevant to forming

dielectric films. However, these references suffer from one or more of the disadvantages discussed below.

Some gate dielectric-forming processes require multiple forming steps. For instance, a dielectric film may be formed by depositing a metal and silicon on a substrate in a first step followed by a second "post deposition step" wherein the composition or structure of the deposited metal/silicon film is modified to achieve the desired final composition of a MSION gate dielectric film. An example of a post deposition step is rapid thermal annealing in an environment that is filled of nitrogen or ammonia. Because control of the film composition is important in dielectric film deposition processes, the fewer the steps, the better the control of the process, and the higher the quality (reflected by dielectric constant, density, contamination, composition and other quality control properties) and conformality (the ability of the film to evenly deposit on all surfaces and shapes of substrate) of the dielectric film.

It is known in the art that any silicon sources that contain carbon in the ligands can lead to carbon in the film and result in degraded electrical properties. Furthermore, any chlorine incorporated in dielectric films is undesirable due to its harmful effect on the electrical properties of the film and the stability of the chlorine in the film (the stability makes it hard to remove chlorine from the dielectric film). Also, the presence of chlorine in the silicon or metal source results in the generation of chloride based particulates in the reaction chamber and deposits in the exhaust system. Thus, to achieve the ideal electrical properties and to minimize particulate generation and tool downtime due to exhaust system cleaning, it is desirable to deposit dielectric films from precursors free of carbon or chlorine in the atomic structure.

The physical properties of a MSION dielectric film are affected by the metal (M) to silicon (Si) ratio, or M/Si. It is desirable to be able to control the

M/Si ratio over a broad range. Thus, it is important to be able to vary the metal and silicon feed independently to achieve the broadest possible M/Si ratios. Some processes use a silicon source precursor that also contains some amount of the metal that is to be deposited. The problem
5 encountered is that changes in the metal-containing silicon source precursor feed rate changes the total amount of the metal fed to the process (due to the metal contained in the silicon precursor). This limits the controllability of the deposition process because the silicon feed rate cannot be changed without also affecting the total amount of metal being
10 fed to the deposition chamber. Furthermore, the ratio of M/Si that can be fed is limited by the composition of the metal in the silicon source precursor. Thus a change in desired M/Si ratio can require changing precursor solutions being fed to the process.

Vaporizing silicon precursor streams can also lead to problems with
15 film composition control. Referring to Fig. 2, some processes in the art use a vaporizer to vaporize the liquid silicon source. The vaporized stream is then fed to the deposition chamber. When the metal source and the silicon source are supplied in liquid form, they must both be vaporized before being introduced into the deposition chamber. Vaporizing two different
20 streams can lead to variable feed concentrations and formation of silicon or metal residues in the vaporizer that can adversely affect the conformality of the film composition. Differences in vaporization of the silicon and metal sources can also lead to compositional gradients in the dielectric.

Bubbling a carrier gas through a liquid precursor can also cause
25 quality problems. In some processes, a silicon source is fed by bubbling a carrier gas through a liquid silicon source. A vaporizer is not used in these processes because the vapor pressure of the silicon source is high enough to be transported as a vapor in a mixture with the carrier gas. In these processes, the composition of the stream transporting the silicon source to

the deposition chamber can vary with temperature and pressure in the bubbling system. This variability in stream composition leads to variability in the composition of the dielectric film, which is a significant quality control issue.

5 For the foregoing reasons, it is desirable to form a dielectric film of the final desired composition in a single forming step. Furthermore, the film should be free of any chlorine and contain as little carbon as possible in the molecular structure. It is also desirable to use a silicon source that is free of any deposition metals so the silicon source feed and the metal source feed
10 may be independently controlled. Finally, it is desirable to have a silicon source that is in the vapor phase at process feed conditions to avoid the need to vaporize a liquid silicon source or bubble a carrier gas through a liquid source.

15 Summary

The current invention is directed to methods and compositions that satisfy the need to form a thin MSiON dielectric film with high electrical qualities (large dielectric constant and low leakage current), and high conformality. The current invention avoids using multiple
20 forming steps to assure uniform coverage and high conformality. Furthermore, the current invention provides a film that is free of chlorine and contains a minimum amount of carbon, both of which can degrade the electrical properties of the film. In addition, the current invention provides the ability to control the M/Si ratio in MSiON films
25 over a broad range without changing precursor solutions. Finally, the current invention avoids the quality and conformality issues that can occur when vaporizing a liquid precursor solution containing multiple components or bubbling a carrier gas through a liquid silicon source.

The high-k MSiON dielectric film of the current invention is formed by vaporizing a metal source followed by feeding a plurality of dielectric precursors (dielectric precursors being the vaporized metal source, a silicon source, an oxygen source, and a nitrogen source) to a deposition device, and forming a dielectric film with the desired final composition in a single forming step. In other words, there is no need for a post deposition step to achieve the desired final composition the dielectric film. Feeding of a plurality of dielectric precursors to the deposition device is effectively concurrent. The high-k dielectric film forms on a silicon substrate in a single forming step without using a post deposition step to adjust the composition of the dielectric precursors in the dielectric film. The resulting high-k dielectric film has the desired MSiON composition, is absent chlorine, and the carbon incorporation is minimized to provide the highest quality dielectric properties.

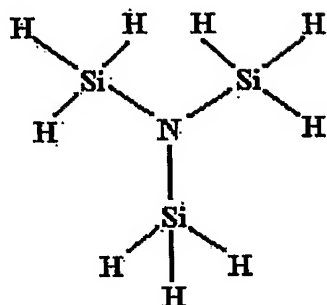
The current invention uses a vapor phase silicon precursor in conjunction with a liquid phase metal precursor for the deposition of MSiON films of desired stoichiometry. The vapor phase silicon precursor is sufficiently volatile at temperatures above 15° C to supply the process as a vapor without bubbling a carrier gas through a liquid or heating in a vaporizer. This eliminates the control and quality problems associated with having to vaporize two precursors (a metal containing precursor and a silicon containing precursor) or bubble a carrier gas through a liquid to feed the silicon source. In addition, the vapor phase silicon precursor is not coordinated to a metal allowing independent control over feeding of the metal source and the silicon source. Thus, the M/Si ratio can be easily varied over a wide range without having to mix new precursor solutions and recalibrate the process to the new precursor mixture. Furthermore, the vapor phase silicon precursor is carbon and chlorine free, eliminating the undesirable effects of carbon and chlorine in the dielectric film. Finally, the

current inventive method produces a dielectric film of the desired final composition is a single step.

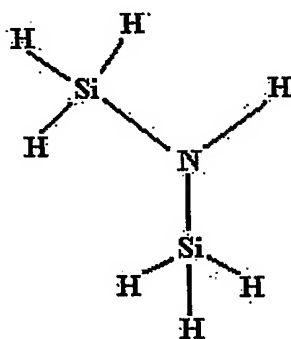
The metal source in a MSiON film is typically a liquid precursor solution. The liquid phase precursor is injected into a system that vaporizes
5 it into a gas phase. The vaporized precursor enters the deposition chamber where deposition occurs at an elevated temperature.

The silicon source of a MSiON film of the current invention is injected into the deposition chamber effectively concurrent with the vaporized metal precursor. The silicon source is in the vapor phase at
10 process feed conditions. That is, the silicon source flows from the source container through the feed measurement and control system as a vapor without the need to be vaporized or without using a carrier gas. However, a gas phase inert may be used to dilute the silicon mixture if needed to obtain accurate flow measurements. Furthermore, the silicon source does not
15 have any atoms of carbon, chlorine, or deposition metals in the molecular structure of the compound. Preferred silicon sources that are carbon and chlorine free are, but are not limited to, the following compounds or mixtures of the following compounds:

1) Trisilylamine;

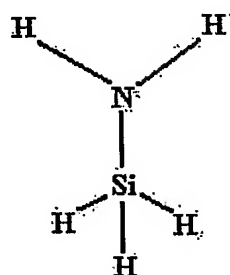


2) Disilylamine;

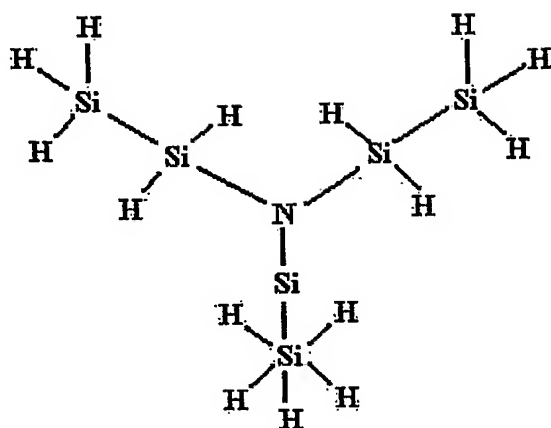


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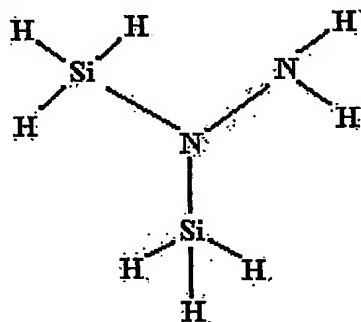
3) Silylamine;



4) Tridisilylamine;

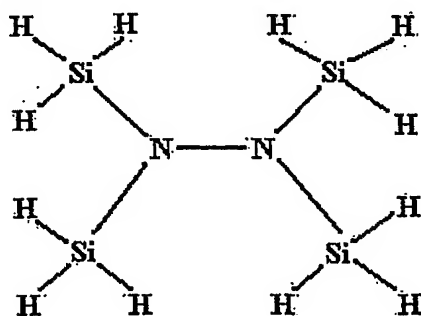


5) Aminodisilylamine;

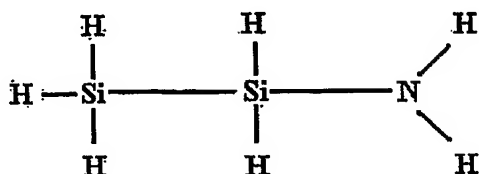


5

6) Tetrasilyldiamine; and



7) Disilane derivatives, wherein any H may be replaced with a NH₂.



The oxygen and nitrogen sources are also injected into the deposition chamber concurrently with the vaporized metal source and the silicon source. Preferred oxygen and nitrogen sources are free of carbon and/or chlorine in their molecular structures.

The reaction of the dielectric precursors in the deposition chamber leads to the formation of a MSiON film on the silicon substrate. The composition of the dielectric film can be precisely controlled by precisely controlling the flow rates of each of the dielectric precursors independently. In a MSiON film, the feed rates of the silicon and metal sources are independently controllable, thus the M/Si ratio of the resulting dielectric film is controllable over a wide range without changing the composition of the metal source or the silicon source.

The reaction of the dielectric precursors in the deposition chamber forms a dielectric film of the desired final composition in a single reaction step. There is no requirement for a post deposition step wherein the composition of the dielectric film is modified by a step after the dielectric precursors are deposited on the substrate.

Because the silicon, oxygen and nitrogen sources in this invention are all carbon and chlorine free, the resulting dielectric film has excellent properties, including a high dielectric constant when combined with a suitable metal in the proper ratio.

Brief Description of the Drawings

FIG. 1 is a flow chart of the steps of the method for forming a MSiON dielectric film.

FIG. 2 is a flow chart of a Prior Art method for forming a MSiON dielectric film.

Description

The present invention is directed to a method of forming and composition of a high-k MSiON dielectric film on semiconductor pieces.

10 The present invention is applicable to chemical vapor deposition and atomic layer deposition processes as well as others known to one skilled in the art.

Referring to the MSiON method of Fig. 1, the vaporizing step 1 comprises vaporizing a metal source to form a vaporized metal source.

15 The metal source of one preferred embodiment is a precursor solution in liquid phase, preferably a dialkylamino, an alkoxy, or an inorganic compound of hafnium (Hf), zirconium (Zr), lanthanum (La), yttrium (Y), gadolinium (Gd), europium (Eu), or praseodymium (Pr). Preparing and vaporizing the liquid phase metal precursor solution is carried out in commercially available equipment under appropriate conditions known to one skilled in the art.

Referring again to the MSiON method of Fig. 1, during the feed step 2 a silicon source, an oxygen source, and a nitrogen source (collectively referred to as the dielectric precursors) are fed to a deposition chamber where a silicon substrate (on which deposition is needed) is placed at an elevated temperature. The deposition chamber is typically maintained between about 300 to about 900°C. Preferably the surface of the work piece in the deposition chamber will be between about 500 to about 600°C. The feeding of the dielectric precursors is effectively concurrent (atomic

layer deposition involves high-speed sequential pulses of feed materials, which for the purposes of this invention is effectively concurrent).

Referring to the MSiON method of Fig. 1, during the feed step 2 of the MSiON method, the silicon source is controllably injected into the deposition chamber effectively concurrent with the vaporized metal source and the other dielectric precursors or silicon film components. In one preferred embodiment, a silicon source is in the vapor phase at process feed conditions. That is, the silicon source of one preferred embodiment has a vapor pressure of greater than approximately 50 torr at 20°C, sufficient to exist in the vapor phase in the feed control system without the need for vaporization or bubbler equipment in the delivery system. Trisilylamine, one preferred silicon source, may be stored as a liquid, but has sufficient vapor pressure (greater than 350 torr vapor pressure at 20°C) to be in the vapor phase in the delivery system without the need to use a vaporizer or bubbler system. Because the silicon source is in the vapor phase, it can be accurately measured and controlled with conventional devices known in the art, and is not affected by deposits in a vaporizer or swings in feed conditions during vaporization of the silicon or metal source.

Still referring to the MSiON method of Fig. 1, preferred embodiments of the feed step 2 include, but are not limited to, the use of a silicon source absent carbon or chlorine in the molecular structure. Thus, the dielectric film has a minimum amount of contained carbon and is free of chlorine, resulting in the optimum electrical properties.

Still referring to the MSiON method of Fig. 1, preferred embodiments of the feed step 2 include, but are not limited to, feeding the oxygen and nitrogen sources into the deposition chamber concurrently with the silicon source. Furthermore, the vaporized metal source is also fed concurrently in the feed step 2. Various preferred embodiments of the MSiON method use nitrogen sources that are free of carbon and/or chlorine in their

molecular structures. It is not required that nitrogen be fed as a separate stream. The nitrogen source can be the same as the metal source, the silicon source, or the oxygen source. Preferred oxygen sources of the current invention are also free of carbon and/or chlorine in their molecular structures. Preferred embodiments include, but are not limited to oxygen, nitrous oxide, or ozone as the oxygen source. The nitrogen source of one preferred embodiment is ammonia. The oxygen and nitrogen sources are fed and controlled with devices known to one skilled in the art.

Referring again to the MSiON method of Fig.1, the deposition and reaction of dielectric precursors in the deposition chamber leads to the formation of a MSiON film on the heated silicon substrate during the forming step 3. One preferred embodiment of a MSiON film is a hafnium silicon oxynitride film or a zirconium silicon oxynitride film formed by feeding a hafnium or zirconium metal using a mixture of a metal source (such as $\text{Hf}(\text{DEA})_4$ or $\text{Zr}(\text{DEA})_4$), trisilylamine, ammonia and nitrous oxide.

Referring again to the MSiON method of Fig. 1, the composition of the MSiON dielectric film can be controlled by varying the flow of each of the dielectric precursors independently during the feeding step 2. Particularly, the feed rate of the silicon source and the metal source are independently controllable because the silicon source does not contain any deposition metals. Thus, the silicon source feed rate can be varied independently of the metal source feed rate to affect the desired metal (M) to silicon (Si) ratio. Similarly, the metal source feed rate can be varied without affecting the silicon source feed rate, also changing the M/Si ratio. Because the feed rate of the silicon and metal sources are independently controllable, the M/Si ratio of the resulting dielectric film is controllable over a wide range without changing the composition of the metal source or the silicon source.

Referring to the MSiON method of Fig. 1, the feeding of the dielectric precursors to the deposition chamber results in the formation of a dielectric film of the desired final composition in a single forming step 3. There is no requirement for a post deposition step wherein the composition or structure
5 of the dielectric film is modified after some or all of the dielectric precursors are deposited on the substrate to achieve the desired final composition.

Although the present invention has been described in considerable detail with reference to certain preferred versions thereof, other versions are possible. For example, the composition and method may be practiced
10 in a process other than chemical vapor deposition or atomic layer deposition. In addition, the deposition of dielectric films can be accomplished at a variety of temperature and conditions. Furthermore, the invention may include a variety of metal, silicon, oxygen and nitrogen sources known in the art. Therefore, the spirit and scope of the appended
15 claims should not be limited to the description of one of the preferred versions contained herein. The intention of the applicants is to cover all modifications, equivalents, and alternatives falling within the spirit and scope of the invention as defined by the appended claims.

What is claimed is:

1. A method for forming a MSiON dielectric film comprising the steps of:
vaporizing a metal source to form a vaporized metal source;
5 feeding a plurality of dielectric precursors to a deposition device,
wherein said dielectric precursors comprise said vaporized metal source, a silicon source, an oxygen source, and a nitrogen source; and
forming a dielectric film, wherein said dielectric film is formed with the
10 desired final composition absent a post deposition step.
2. The method of claim 1, wherein said silicon source comprises a molecular structure absent carbon.
- 15 3. The method of claim 1, wherein said silicon source comprises a molecular structure absent chlorine.
4. The method of claim 1, wherein said silicon source is the vapor phase in the delivery system.
- 20 5. The method of claim 1, absent a step wherein said silicon source is vaporized.
6. The method of claim 1, absent a step wherein said silicon
25 source is delivered by bubbling a gas through a liquid silicon source.
7. The method of claim 1, wherein said silicon source has a vapor pressure of at least about 50 torr at 20°C.

8. The method of claim 1, wherein said silicon source is selected from the group consisting of trisilylamine, disilylamine, silylamine, tridisilylamine, aminodisilylamine, tetrasilyldiamine, disilane, derivatives of disilane, and mixtures thereof.

5

9. The method of claim 1, wherein said silicon source is trisilylamine.

10

10. The method of claim 1, wherein said oxygen source comprises a molecular structure absent carbon.

11. The method of claim 1, wherein said oxygen source comprises a molecular structure absent chlorine.

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12. The method of claim 1, wherein said oxygen source is selected from the group consisting of oxygen, nitrous oxide, ozone, and mixtures thereof.

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13. The method of claim 1, wherein said nitrogen source comprises a molecular structure absent carbon.

14. The method of claim 1, wherein said nitrogen source comprises a molecular structure absent chlorine.

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15. The method of claim 1, wherein said nitrogen source is the same as said metal source, said silicon source, or said oxygen source.

16. The method of claim 1, wherein said nitrogen source is ammonia.

17. The method of claim 1, wherein said metal source is selected from the group consisting of a dialkylamino, and alkoxy.

18. The method of claim 1, wherein said metal source is an
5 inorganic compound selected from the group consisting of hafnium (Hf), zirconium (Zr), lanthanum (La), yttrium (Y), gadolinium (Gd), europium (Eu), praseodymium (Pr), and mixtures thereof.

19. The method of claim 1, wherein the amounts of said metal
10 source and said silicon source in said desired final composition of said dielectric film are independently controllable.

20. The method of claim 1, wherein said forming a dielectric film
15 step is completed using a chemical vapor deposition process.

21. The method of claim 1, wherein said forming a dielectric film
step is completed using an atomic layer deposition process.

22. A MSiON dielectric film prepared by a process comprising the
20 steps of:
vaporizing a metal source to form a vaporized metal source;
feeding a plurality of dielectric precursors to a deposition device,
wherein said dielectric precursors comprise said vaporized metal
source, a silicon source, an oxygen source, and a nitrogen
25 source; and
forming a dielectric film, wherein said dielectric film is formed with the
desired final composition absent a post deposition step.

23. The dielectric film of claim 22, wherein said silicon source comprises a molecular structure absent carbon.

24. The dielectric film of claim 22, wherein said silicon source
5 comprises a molecular structure absent chlorine.

25. The dielectric film of claim 22, wherein said silicon source is in the vapor phase in the delivery system.

10 26. The dielectric film of claim 22, absent a step wherein said silicon source is vaporized.

27. The dielectric film of claim 22, absent a step wherein said silicon source is delivered by bubbling a gas through a liquid silicon source.

15 28. The dielectric film of claim 22, wherein said silicon source has a vapor pressure of at least about 50 torr at 20°C.

20 29. The dielectric film of claim 22, wherein the source of said silicon is selected from the group consisting of trisilylamine, disilylamine, silylamine, tridisilylamine, aminodisilylamine, tetrasilyldiamine, disilane, derivatives of disilane, and mixtures thereof.

25 30. The dielectric film of claim 22, wherein the source of said silicon is trisilylamine.

31. The dielectric film of claim 30, wherein said metal source comprises hafnium.

32. The dielectric film of claim 31, wherein said oxygen source comprises nitrous oxide.

5 33. The dielectric film of claim 32, wherein said nitrogen source comprises ammonia.

34. The dielectric film of claim 22, wherein said oxygen source comprises a molecular structure absent carbon.

10 35. The dielectric film of claim 22, wherein said oxygen source comprises a molecular structure absent chlorine.

15 36. The dielectric film of claim 22, wherein said oxygen source is selected from the group consisting of oxygen, nitrous oxide, ozone, and mixtures thereof.

37. The dielectric film of claim 22, wherein said nitrogen source comprises a molecular structure absent carbon.

20 38. The dielectric film of claim 22, wherein said nitrogen source comprises a molecular structure absent chlorine.

25 39. The dielectric film of claim 22, wherein said nitrogen source is the same as said metals source or said silicon source, or said oxygen source.

40. The dielectric film of claim 22, wherein said nitrogen source is ammonia.

41. The dielectric film of claim 22, wherein said metal source is selected from the group consisting of a dialkylamino, and alkoxy.

5 42. The dielectric film of claim 22, wherein said metal source is an inorganic compound selected from the group consisting of hafnium (Hf), zirconium (Zr), lanthanum (La), yttrium (Y), gadolinium (Gd), europium (Eu), praseodymium (Pr), and mixtures thereof.

Abstract

This disclosure discusses the forming of gate dielectrics in semiconductor devices, and more specifically to forming thin high-k dielectric films on silicon substrates typically using chemical vapor deposition or atomic layer deposition processes. The current invention
5 forms a high-k dielectric film in a single film-forming step using a vapor phase silicon precursor in conjunction with a liquid phase metal precursor, a nitrogen source and an oxygen source for the deposition of a metal silicon oxy nitride (MSiON) film of desired stoichiometry.

10 The vapor phase silicon precursor is not coordinated to a metal allowing independent control over feeding of the metal source and the silicon source. Thus, the M/Si ratio can be easily varied over a wide range. Furthermore, the vapor phase silicon precursor, liquid phase metal precursor, nitrogen source and oxygen sources are chlorine
15 free, eliminating the undesirable effects chlorine in the dielectric film and chloride by products in the reaction chamber and exhaust system. Furthermore, the vapor phase silicon precursor, nitrogen source and oxygen sources are carbon free, minimizing the incorporation of carbon in the dielectric film.

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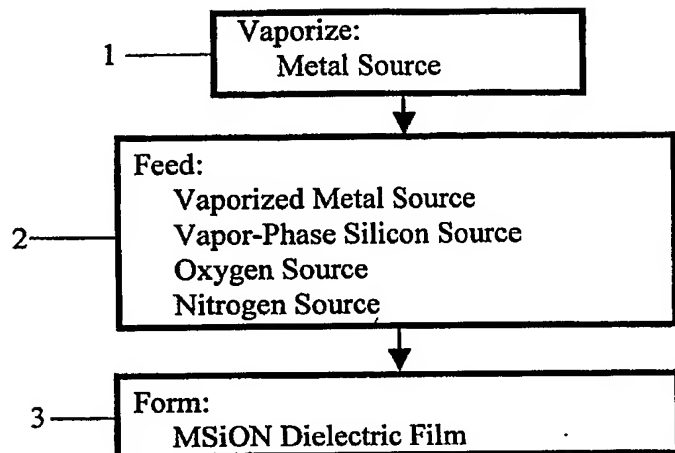
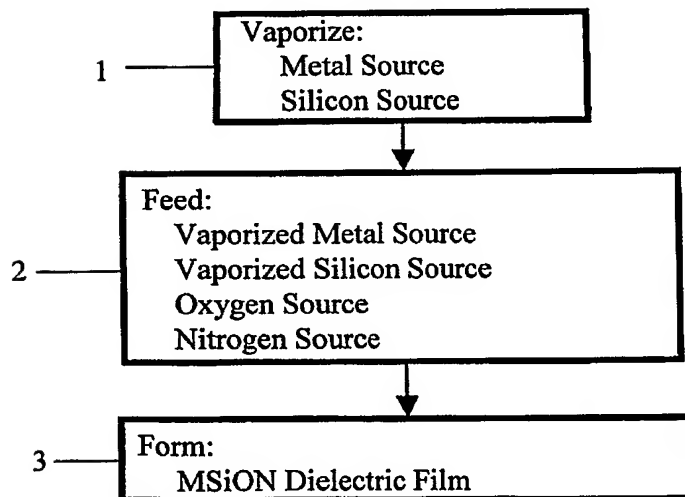


FIG. 1



PRIOR ART

FIG. 2